

ABSTRACT OF THE DISCLOSURE

An interposer assembly includes a dielectric plate having a plurality of contact passages extending through the plate with a contact in each passage. Each contact includes a pair of laterally spaced contact points at the top and bottom of the plate. Sandwiching of the interposer assembly between two substrates brings the contact points on each spring arm into engagement with a pad, elastically bends the contacts and forms redundant high pressure wiped electrical connections between the contact points and pads.